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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

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## Transistors

**2SB0976 (2SB976)**

## Silicon PNP epitaxial planar type

For low-frequency output amplification

For DC-DC converter

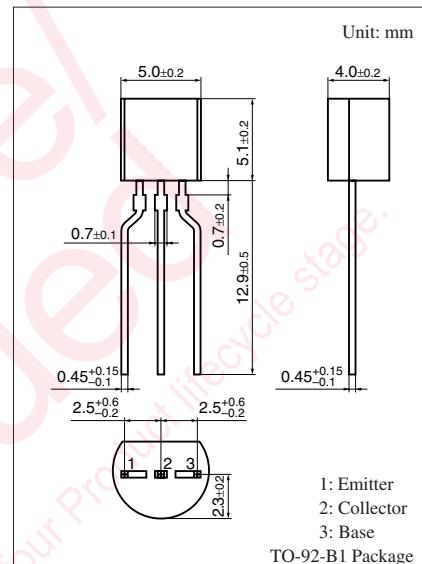
For stroboscope

**■ Features**

- Low collector-emitter saturation voltage  $V_{CE(sat)}$
- Large collector current  $I_C$

**■ Absolute Maximum Ratings**  $T_a = 25^\circ\text{C}$ 

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	$V_{CBO}$	-27	V
Collector-emitter voltage (Base open)	$V_{CEO}$	-18	V
Emitter-base voltage (Collector open)	$V_{EBO}$	-7	V
Collector current	$I_C$	-5	A
Peak collector current	$I_{CP}$	-8	A
Collector power dissipation	$P_C$	0.75	W
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$



TO-92-B1 Package

**■ Electrical Characteristics**  $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$ 

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-emitter voltage (Base open)	$V_{CEO}$	$I_C = -1 \text{ mA}, I_B = 0$	-18			V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_E = -10 \mu\text{A}, I_C = 0$	-7			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = -10 \text{ V}, I_E = 0$			-100	nA
Emitter-base cutoff current (Collector open)	$I_{EBO}$	$V_{EB} = -5 \text{ V}, I_C = 0$			-1	$\mu\text{A}$
Forward current transfer ratio <sup>1, 2</sup>	$h_{FE}$	$V_{CE} = -2 \text{ V}, I_C = -2 \text{ A}$	125		625	—
Collector-emitter saturation voltage <sup>1</sup>	$V_{CE(sat)}$	$I_C = -3 \text{ A}, I_B = -0.1 \text{ A}$		-0.4	-1.0	V
Transition frequency	$f_T$	$V_{CB} = -6 \text{ V}, I_E = 50 \text{ mA}, f = 200 \text{ MHz}$		120		MHz
Collector output capacitance (Common base, input open circuited)	$C_{ob}$	$V_{CB} = -20 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		60		pF

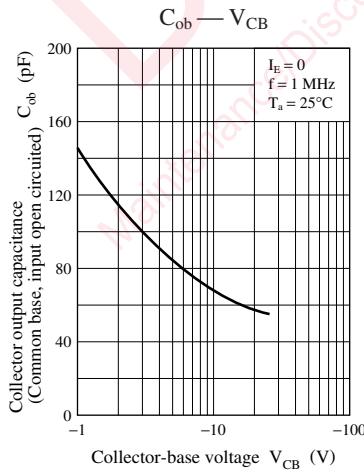
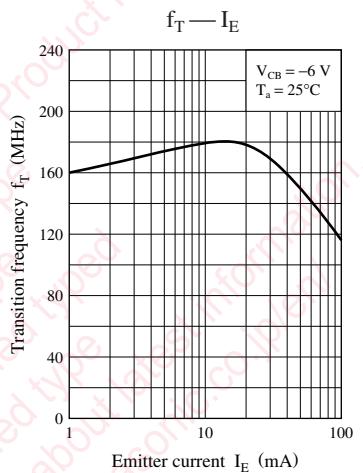
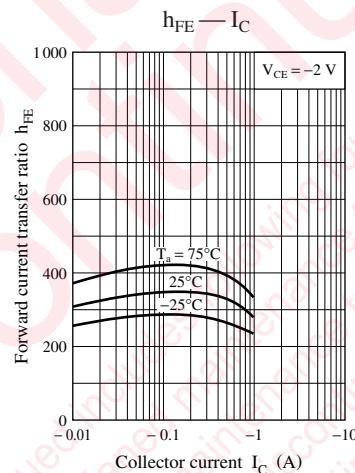
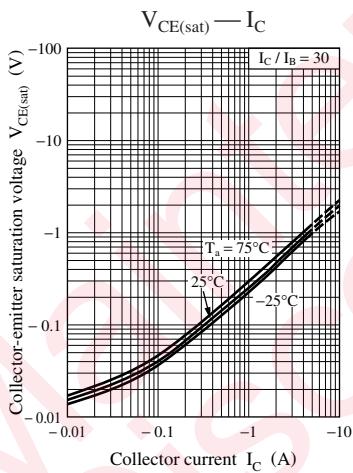
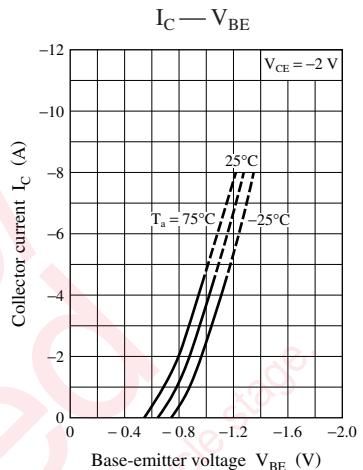
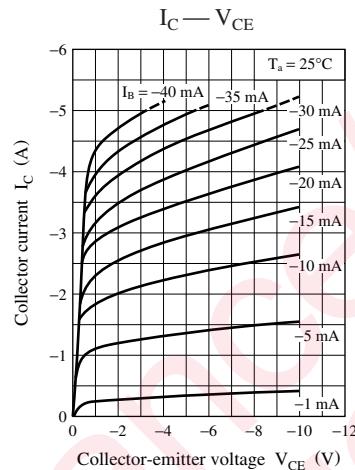
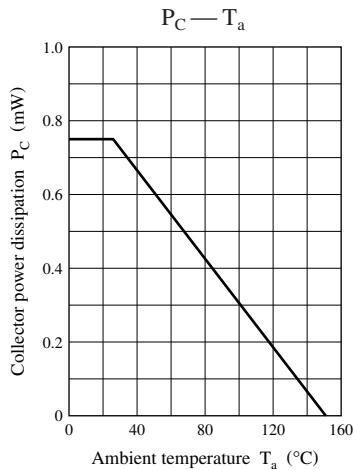
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. \*1: Pulse measurement

\*2: Rank classification

Rank	Q	R
$h_{FE}$	125 to 205	180 to 625

Note) The part number in the parenthesis shows conventional part number.



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